

## REMARKS/ARGUMENTS

The applicant's attorneys appreciate the Examiner's comments.

Enclosed herewith is a new Oath. Entry of the new Oath is requested.

In the Office Action, it has been stated that Kagawa shows "at least one power device (6)" and "a lead frame (3) including a conductive pad having large area to receive the power device." However, as seen in Figure 1(b), power device 6 is disposed on pad 4, which is isolated from conductive pad 3. Thus, as noted in the previous papers, Kagawa does not show a power module in which the power device resides on a pad that is integral with a lead.

Furthermore, claim 1 calls for a conductive pad, "said conductive pad having a first open surface area large enough to receive said at least one power semiconductor device and a second open surface opposite said first open surface exposed through said opening in said housing element."

It has been stated in the Office Action that "The housing element (13) in Kagawa does not have the bottom portion; that is the opening in the housing element through which a surface of the conductive pad opposite to the surface on which the die resides is exposed."

It appears that the Office Action confirms that Kagawa does not anticipate claim 1.

For the above reasons, and other reasons set forth in the record, it is respectfully submitted that Kagawa does not anticipate claim 1, and claims depending from claim 1.

Reconsideration is requested.

The application is believed to be in condition for allowance. Such action is earnestly solicited.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on September 19, 2005:

Kourosh Salehi

Name of applicant, assignee or  
Registered Representative

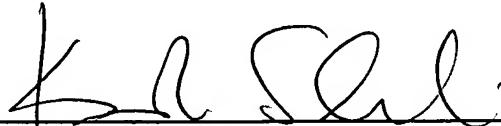
Signature

September 19, 2005

Date of Signature

SHW:KS:ck

Respectfully submitted,



Kourosh Salehi

Registration No.: 43,898

OSTROLENK, FABER, GERB & SOFFEN, LLP

1180 Avenue of the Americas

New York, New York 10036-8403

Telephone: (212) 382-0700


 UNITED STATES OF AMERICA  
 COMBINED DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

 OFCIS FILE NO.  
 IR-2553 CIP  
 (2-3627)

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verify that I am the original, first and sole inventor (if only one name is listed below) or a joint inventor (if plural inventors are named) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

## LOW COST POWER SEMICONDUCTOR MODULE WITHOUT SUBSTRATE

the specification of which is attached hereto, unless the following box is checked:

was filed on August 6, 2003 as United States patent Application Number or PCT International patent application number 10/635,359 and was amended on February 22, 2005 (if any).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose all information known to be material to patentability in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefits under Title 35, United States Code §119 of any foreign application(s) for patent or inventor's certificate or United States provisional application(s) listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

## Prior Foreign or Provisional Application(s)

COUNTRY	APPLICATION NUMBER	DATE OF FILING (day, month, year)	PRIORITY CLAIMED UNDER 35 U.S.C. 119
U.S.A.	60/175,802	12 JANUARY 2000	YES <input checked="" type="checkbox"/> NO <input type="checkbox"/>
			YES <input type="checkbox"/> NO <input type="checkbox"/>
			YES <input type="checkbox"/> NO <input type="checkbox"/>

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

UNITED STATES APPLICATION NUMBER	DATE OF FILING (day, month, year)	STATUS (patented, pending, abandoned)
09/758,822	11 JANUARY 2001	Patented

I hereby appoint customer no. 2352 OSTROLENK, FABER, GERB & SOFFEN, I.P. and the members of the firm, Samuel H. Weiner - Reg. No. 18,510; Robert C. Faber - Reg. No. 24,322; Max Moskowitz - Reg. No. 30,576; James A. Finder - Reg. No. 30,173; William O. Gray, III - Reg. No. 30,944; Louis C. Dujmich - Reg. No. 30,625, and Douglas A. Mino - Reg. No. 31,643, as attorneys with full power of substitution and revocation to prosecute this application, to transact all business in the Patent & Trademark Office connected therewith and to receive all correspondence.

SEND CORRESPONDENCE TO: **OSTROLENK, FABER, GERB & SOFFEN, LLP** DIRECT TELEPHONE CALLS TO:  
 1180 AVENUE OF THE AMERICAS (212) 382-0700  
 NEW YORK, NEW YORK 10036-8403  
 CUSTOMER NO. 2352

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

FULL NAME OF SOLE OR FIRST INVENTOR <b>WILLIAM GRANT</b>	INVENTOR'S SIGNATURE 	DATE <b>15/SEP/05</b>
RESIDENCE (City and either State or Foreign Country) <b>FOUNTAIN VALLEY, CALIFORNIA 92708</b>	COUNTRY OF CITIZENSHIP <b>U.S.A.</b>	
POST OFFICE ADDRESS <b>1085 LA FONDA CIRCLE, FOUNTAIN VALLEY, CALIFORNIA 92707</b>		
FULL NAME OF SECOND JOINT INVENTOR (if any)	INVENTOR'S SIGNATURE	DATE
RESIDENCE (City and either State or Foreign Country)	COUNTRY OF CITIZENSHIP	
POST OFFICE ADDRESS		

CONTINUED ON PAGE 2